

OSEM Development Update “Show-and-Tell”

Stuart Aston

University of Birmingham for the **UK Advanced LIGO Team**

University of Glasgow

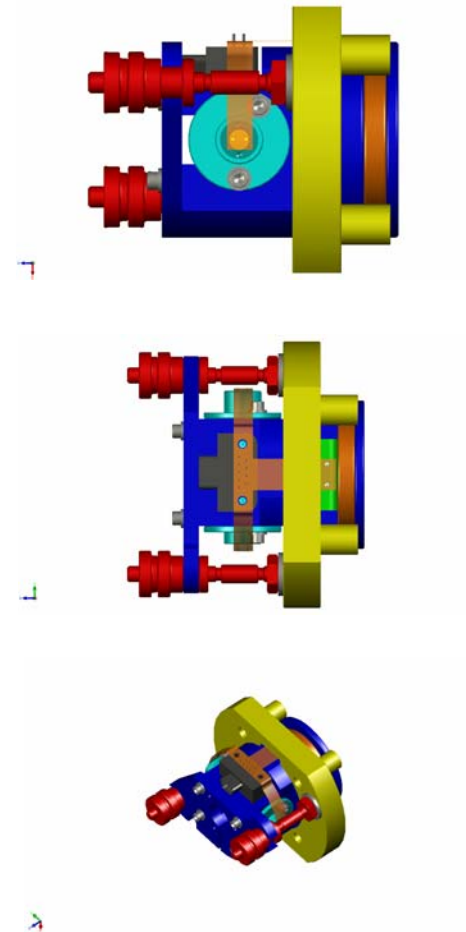
Monolithic Suspension Workshop

Friday 28th January 2005

Latest OSEM Model Located on ALUK Birmingham webpage at:

<http://www.sr.bham.ac.uk/research/gravity/rh,d,2.html>

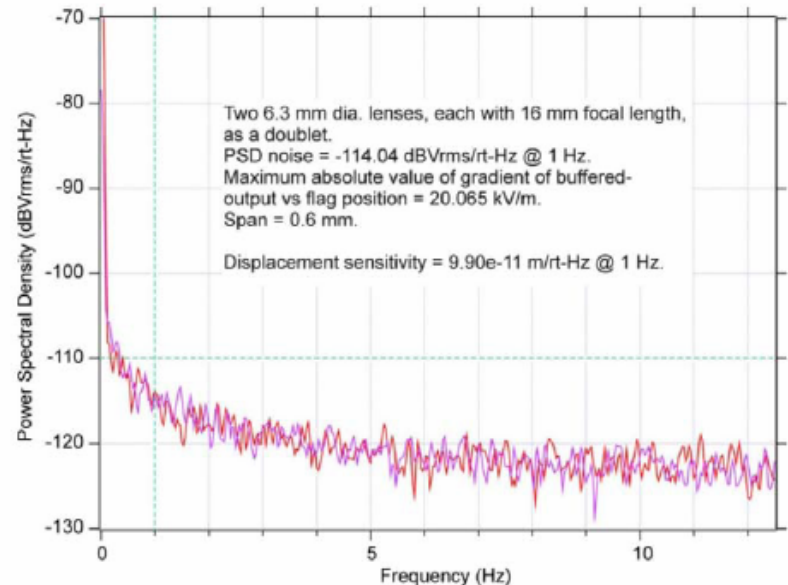
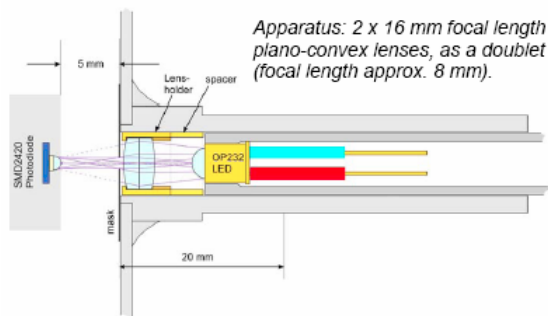
- **OSEM Performance Summary**
 - Required Performance
 - Latest Sensor Performance
- **Current OSEM Design**
 - Sensor Development
 - Inter-Connect Development
 - OSEM Mechanical Adjustment
 - PAM Retro-Fit Implementation
- **Current OSEM Status**
 - Part-Procurement
 - Vacuum Compatibility Testing
- **OSEM Next Steps**



- **Required Range Performance:**
 - 0.35mm (peak-peak) working range ^[1], incorporating:
 - 0.20mm OSEM positioning inaccuracy (adjustment resolution)
 - 0.15mm to cope with drifts in the suspension (thermal etc.)
 - Hybrid OSEM range has been demonstrated to be 0.7mm
 - **We aim for no worse than 0.7mm working range**
- **Required Sensitivity Performance:**
 - $3 \times 10^{-10} m \sqrt{Hz}$ at 1Hz has been demonstrated by the Hybrid OSEM (confirmed by N. Lockerbie ^[2], P. Fritschel and R. Adhikari ^[3])
 - **We aim for no worse than $3 \times 10^{-10} m \sqrt{Hz}$ at 1Hz**

- Current Sensor Performance: *(N. Lockerbie)*

- 0.6mm (peak-peak) working range
- $1 \times 10^{-10} \text{ m} \sqrt{\text{Hz}}$ at 1 Hz



- September 2004: Includes additional emitter lens + mask configuration
- Present: Includes additional emitter & receiver lens + mask configuration
(to aid commonality of sensor parts and assembly)

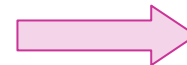
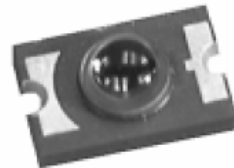
- **Sensor Development:**

- Honeywell Surface-Mount Emitter (SME2470) Replaced with Optek leaded device (OP232)



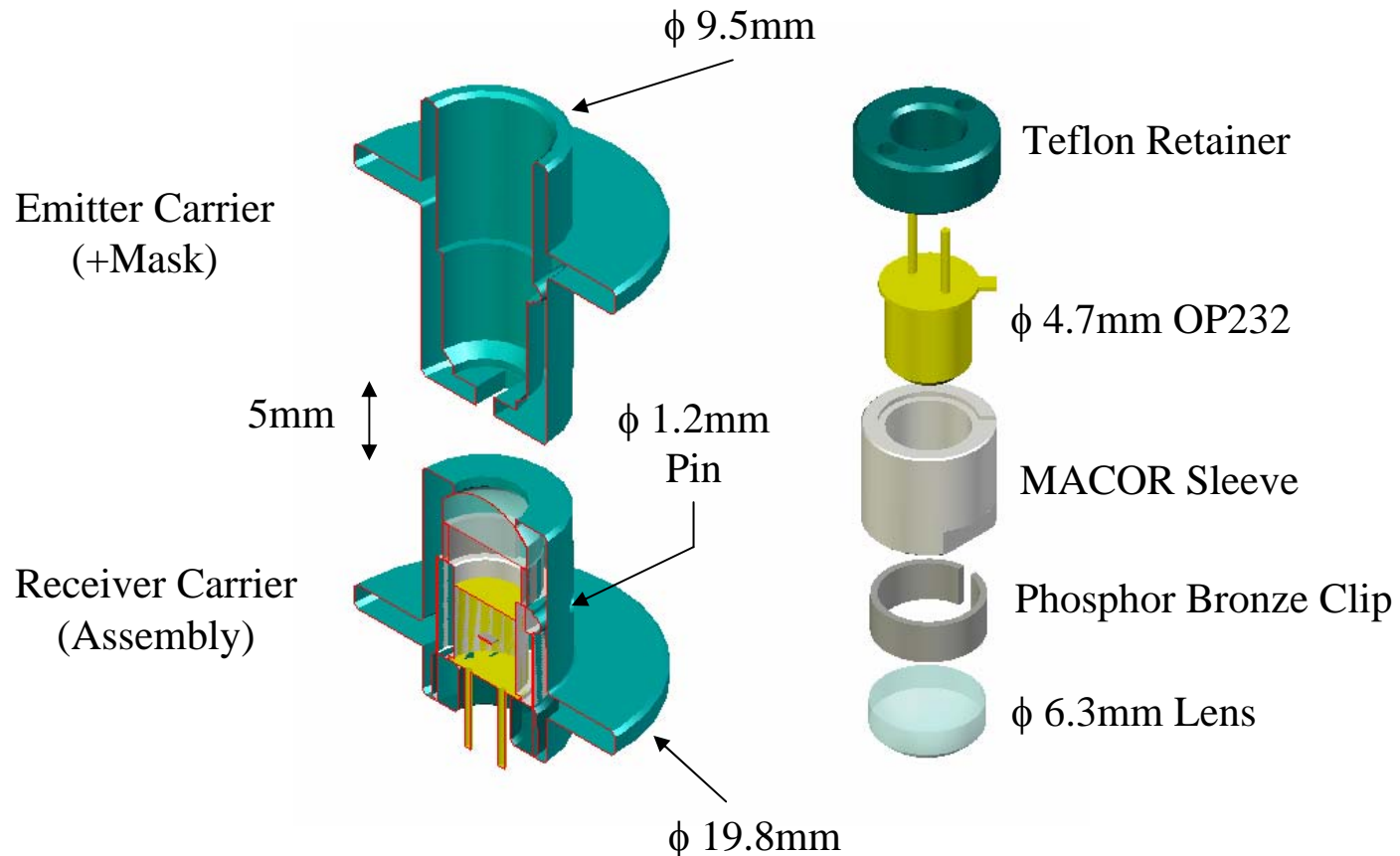
TO-46 Package
Hermetically Sealed
Kovar
(n.b. anode-to-case)

- Honeywell Surface-Mount Receiver (SMD2420) Replaced with Centronics leaded device (BPX65)

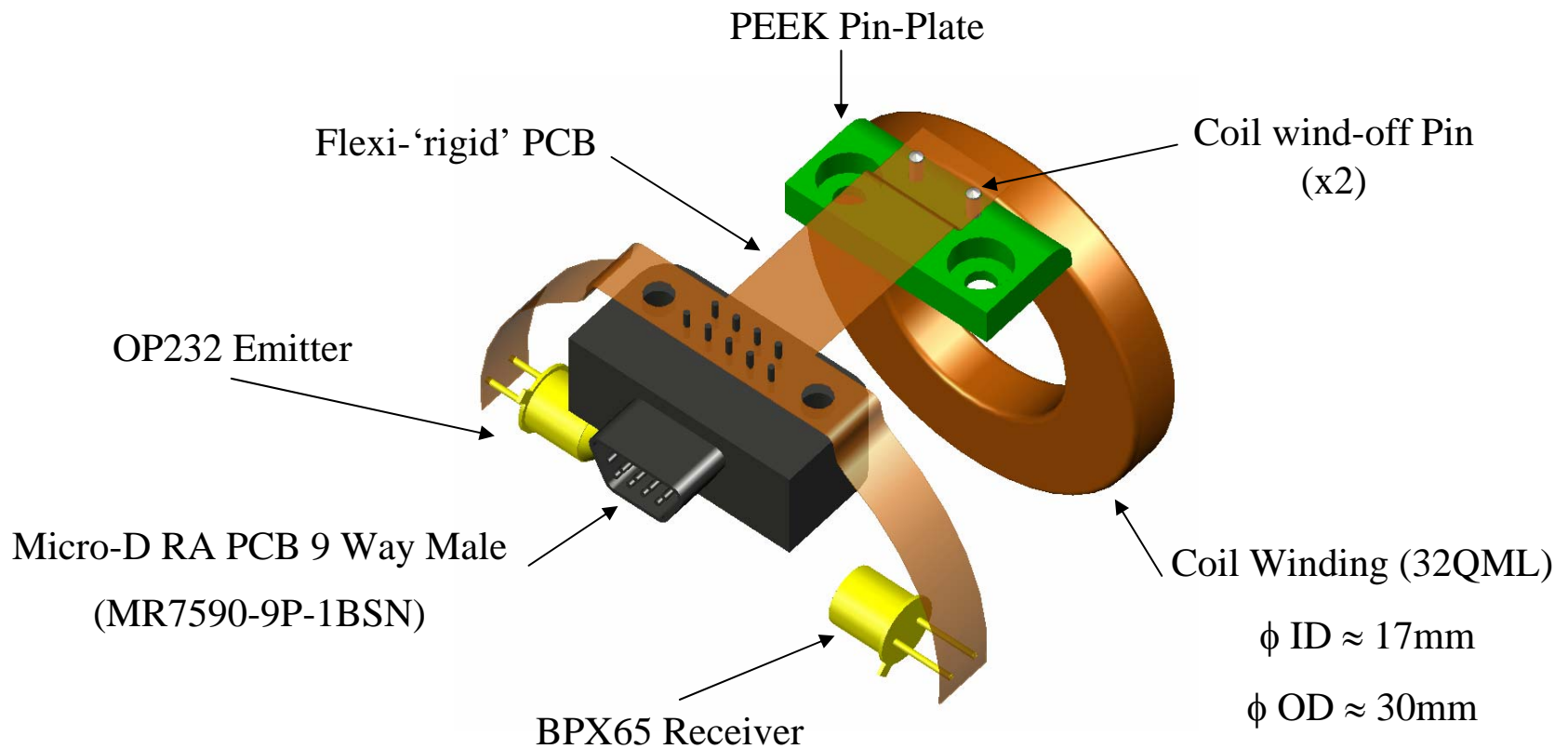


TO-18 Package
Hermetically Sealed
Steel
(n.b. cathode-to-case)

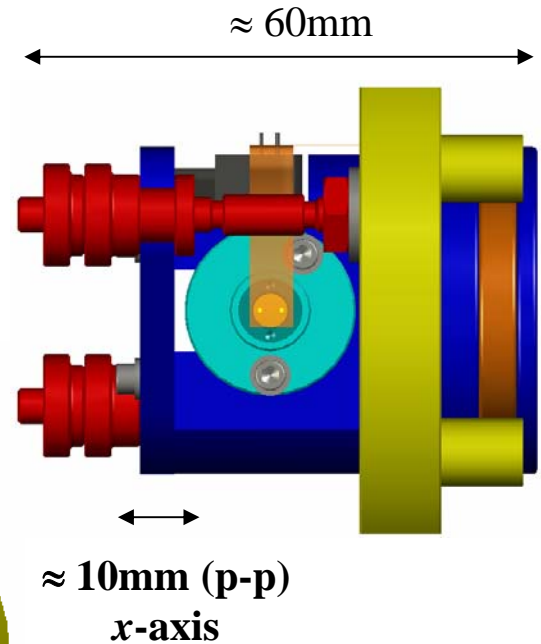
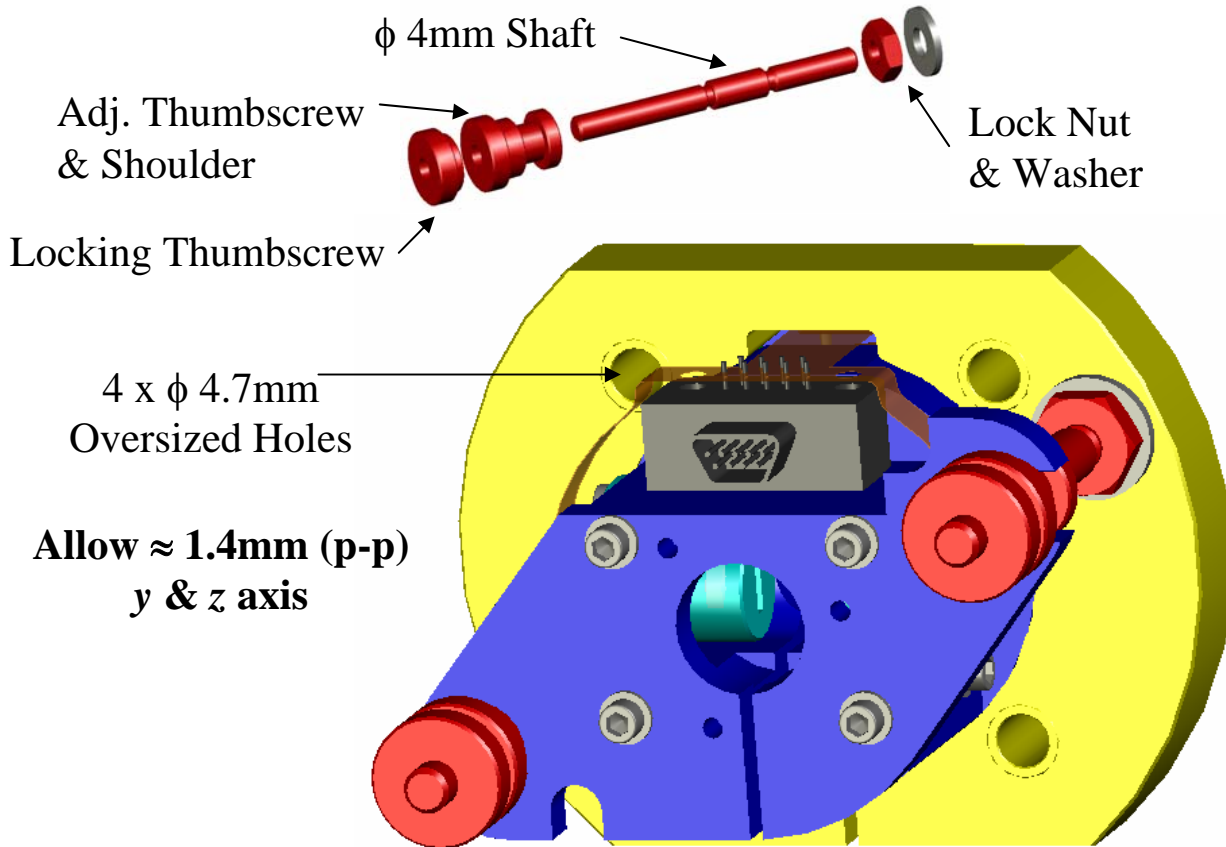
- Sensor Development:



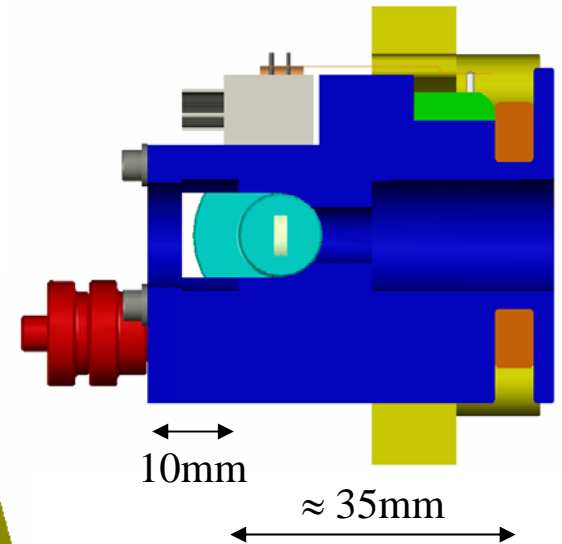
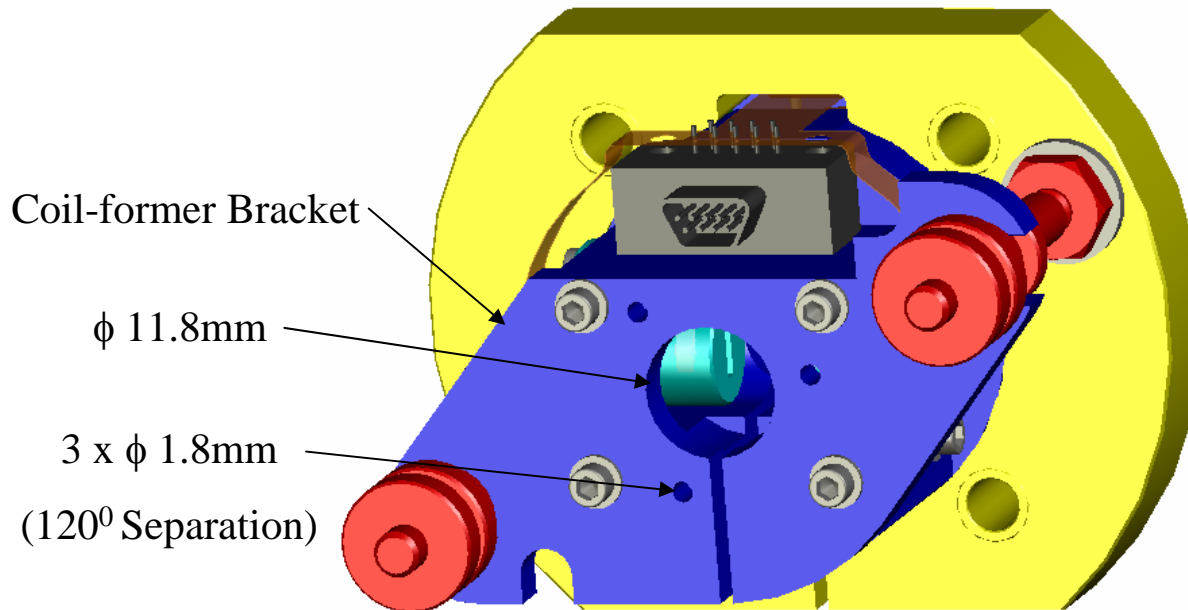
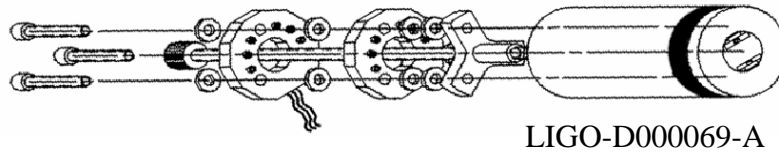
- Inter-Connect Development:



- OSEM Mechanical Adjustment:



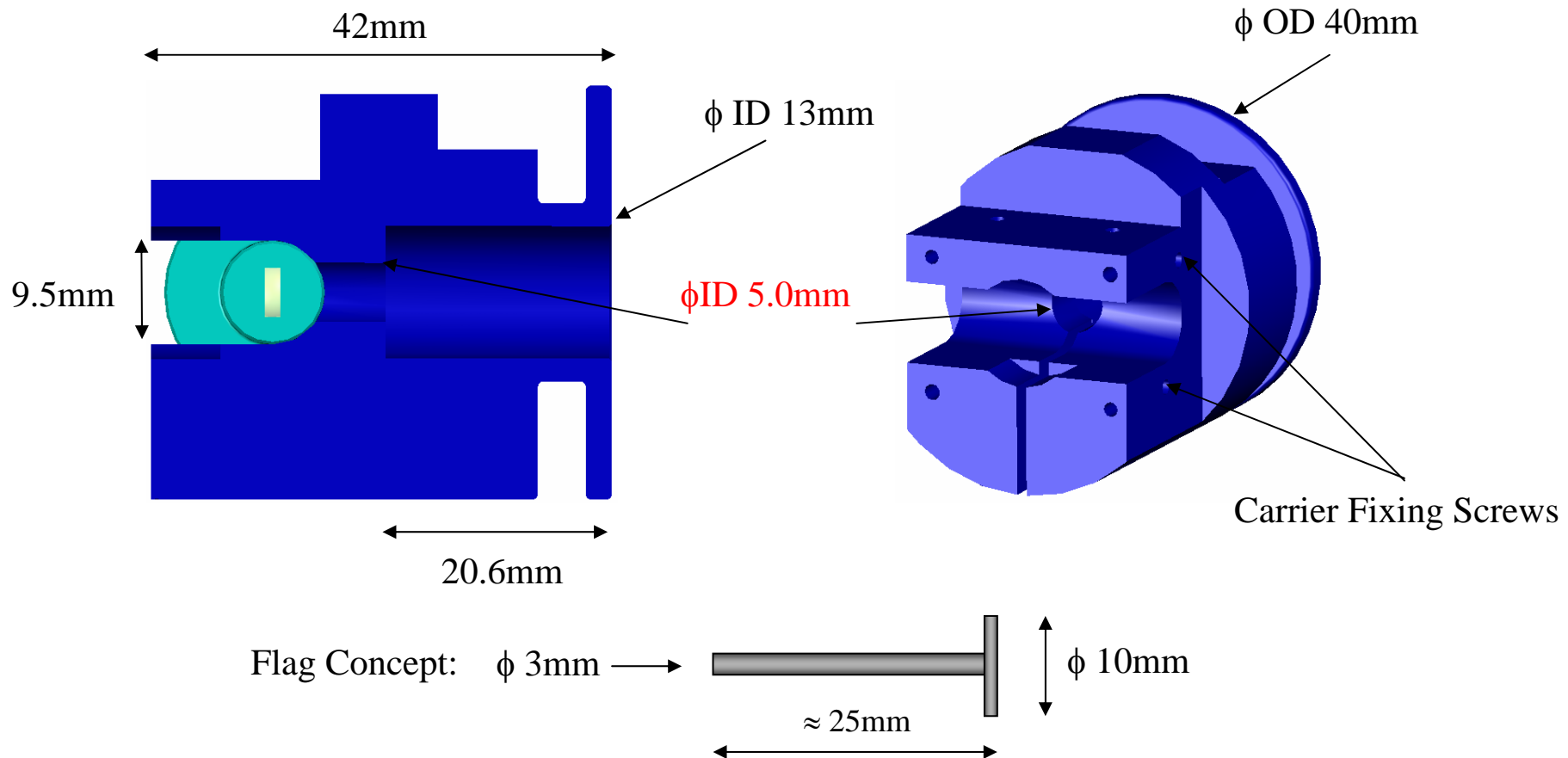
- Pitch Actuation Magnet (PAM) Retro-Fit Implementation:



Initial LIGO Design: 10mm separation between magnets

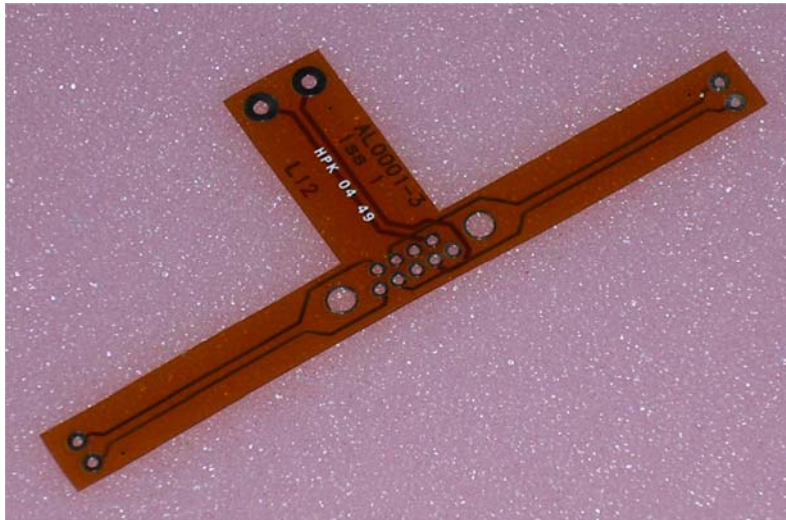
Modified Hybrid OSEM Design: 35mm separation between magnets

- Coil-former Development:



- Flexi-Circuit Part-Procurement Underway:

- Identification of Production issues
 - Inked, No radii on corners
- Vacuum Compatibility Testing
 - Qty. \approx 20 complete units
 - Double Sided? (or Single?)

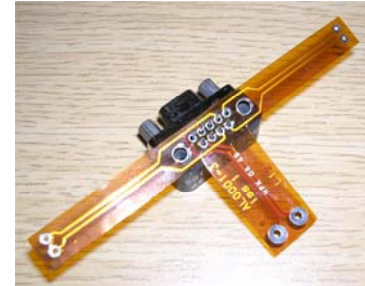


Kapton (25 μ m)	Coverlay
Adhesive (25 μ m)	(DuPont LF0110)
Copper (18 μ m)	Copper Clad Laminate
Adhesive (25 μ m)	
Kapton (25 μ m)	(DuPont LF8515)
Adhesive (25 μ m)	
Copper (18 μ m)	Coverlay
Adhesive (25 μ m)	
Kapton (25 μ m)	

Total Thickness \approx 250 μ m

(10 procured)

- Connector Part-Procurement Underway:
 - Identification of Production issues
 - Inked
 - Vacuum Compatibility Testing
 - Qty. \approx 10-20 units (each connector type?)



RA OSEM Male



LCP Insulator Insert



STR Pigtail Female

Component	Material	Status
Potting Compound	Hysol C9-4215	<i>Helena (Procuring)</i>
Insulator	Liquid Crystal Polymer	<i>Stuart (10 procured)</i>
Interfacial Seal	Flourosilicone	<i>Not Fitted</i>

- **Sensor 'Alignment' Issues**

- We presently have no mechanical adjustment for the alignment of the sensor optical components
- However, we are confident that the emission pattern of the OP232 is consistent (device-to-device) within the batch of 25 units tested (N. Lockerbie, Oct 04). Further batch-to-batch testing is also available, if deemed to be necessary (n.b. fixed device orientation)
- Possible device-to-device variability in radiated intensity
- Manufacturer unable to supply graded devices (≈ 1000 off)
- Potential solution via drive electronics

➤ **We would wish to test and characterise performance of the prototype OSEM's (e.g. by obtaining the 'spread' of sensor transfer functions)**

- **Thermal Issues:**
 - Electrical isolation of the sensor packages leads to a reduction in the thermal link to the coil-former (via Macor sleeve)
 - Not clear if this has a significant impact upon the temperature stability of the device
- **We may wish to further investigate thermal effects by characterising the performance of the device in vacuum, and in a temperature controlled environment (e.g. Bham thermal vacuum chamber)**



- Further Questions / Issues:
 - Are thread inserts (brass / steel) required to hold 'reliable' threads in aluminium?
 - Are any coatings applied to any parts?
 - Current design omits any clearance holes in the coil-former clamp & bracket for access to earthquake stops etc. (We intend to use the MC controls prototype design as a template)

- **Prototype Production:**
 - Possible in-house production of prototype devices
 - A few coil-formers, but additional sensor assemblies
 - Would expect to have these produced in time for the LSC
- **Further Testing:**
 - Carry out any performance characterisation as required (including any thermal analysis / testing)
- **Part-Procurement:**
 - Place orders for more substantial quantities of components (i.e. sufficient to fulfil vacuum compatibility testing requirements)
 - Flexi-circuit
 - Connectors (both OSEM and Pigtail mating connector)
 - Sensor Components (OP232 & BPX65)
 - Submit for Vacuum Compatibility Testing